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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kuznetsov, et al.) Group Art Unit Unknown
Appl. No. : Unknown)
Filed : Herewith) I hereby certify that this correspondence and all
For : METHOD FOR) marked attachments are being deposited with
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Examiner : Unknown) Commissioner for Patents, Washington, D.C.
20231, on 11/6/01
Gordon H. Olson, Reg. No. 20,319

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

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Dear Sir:

Prior to examination of the above-captioned application, please amend the application as follows:

IN THE SPECIFICATION:

Please amend the specification, published as International Application WO 00/68977, as follows:

On page 1, line 2, please insert --Field of the Invention--.

Please amend the paragraph beginning on page 1, line 3, as follows:

The present invention relates to a method of transferring a wafer between a thermal treatment chamber and a thermal treatment installation.

Background of the Invention

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GROUP 3600